



IFW

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Richard W. Wensel

**Serial No.:** 10/600,149

**Filed:** June 19, 2003

**For:** SEMICONDUCTOR DIE WITH  
ATTACHED HEAT SINK AND  
TRANSFER MOLD

**Examiner:** N. Ha

**Group Art Unit:** 2811

**Attorney Docket No.:** 2269-3061.8US  
(96-0893.07/US)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

August 3, 2004  
Date

Signature

Deborah L. Hendricks  
Name (Type/Print)

**AMENDMENT**

MAIL STOP AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This amendment is in response to the Office Action of May 4, 2004 whose initial period of response is set to expire on August 4, 2004.

**The listing of claims** begins on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.